SPECIFICATION FOR APPROVAL
产品承认书

CUSTOMER:

CUSTOMER NO. :

HSW PART NO. : HSW-H2401S

DESCRIPTION: 100/1000M 网络滤波器

ATTACHMENT:

■ SPECIFICATION

■ SAMPLE Q'TY OF SAMPLES 5 PCS

CUSTOMER APPROVAL (客户承认章)		**HSW APPROVAL** (公司承认章)	
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PLEASE REPLY THIS SHEET TO US AFTER SIGNATURE(请签字后回传本页)

10/100/1000 BASE-T SINGLE PORT MAGNETICS MODULES

- ●Meets IEEE 802.3af and ANSIX3.263 standards
- ●Suitable For End-span and Mid-span PoE Applications
- ●RoHS Compliant
- ●10/100/1000 Base-T,Surface Mount Type,Open Header
- ●Operating temperature range: 0℃ to +70℃
- ●Storage temperature range: -25℃ to +125℃

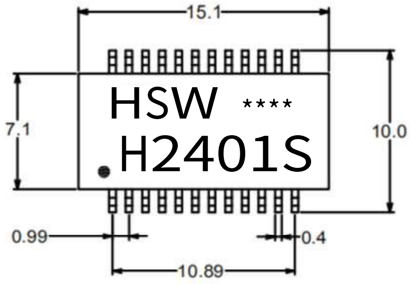
Electrical Specifications @25℃

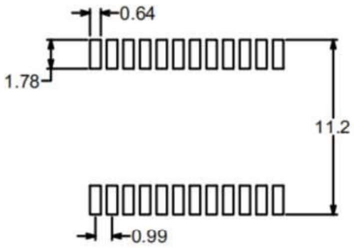
Part Number	OCL(uH min) @100KHz/0.1V	Turns Ratio	Cross talk (dB min)		**HI-POT**
	with 8mA DC Bias	(±5%)	0.5-40MHz	40.1-100MHz	**(V)**
HSW-H2401S	350	1CT:1CT	-35	-33-20*LOG(f/50)	**1500**

continue

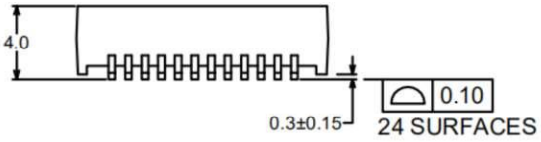
Part Number	Insertion Loss	Return Loss		CMRR
	(dB max)	(dB min)		(dB min)
	0.5-100MHz	0.5-40MHz	40.1-100MHz	0.5-100MHz
HSW-H2401S	-1.1	-18	-12+20 log(f/80)	-30

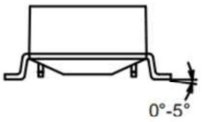
MECHANICAL





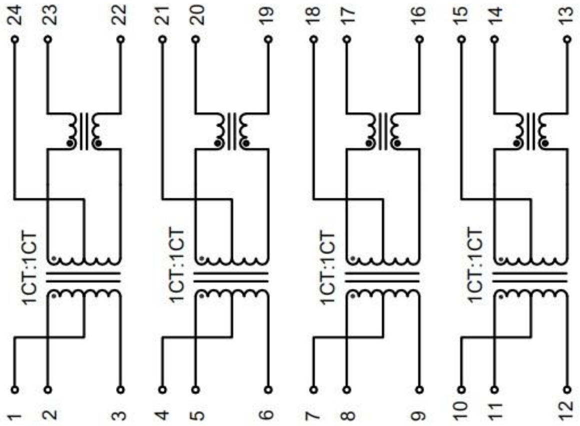
SUGGESTED PAD LAYOUT



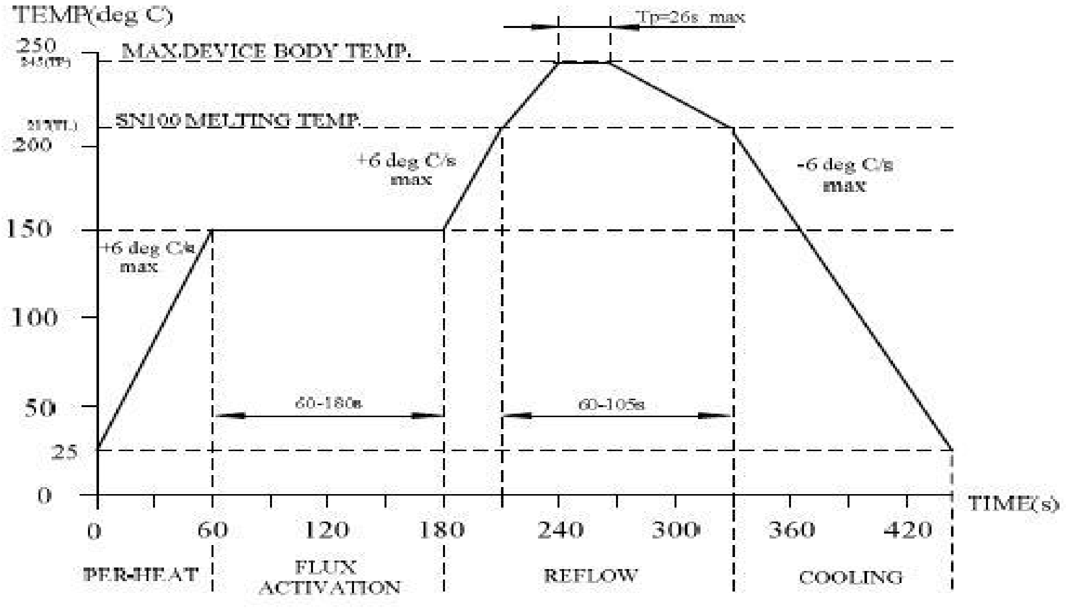


SCHEMATICS

Unless otherwise specified all tolerances are: ±0.25 in mm



Recommended Lead Free IR Reflow Soldering Curve:



COMPONENT BODY REFLOW TEMPERATURE PROFILE

Item	Soldertechnique simulation	Temperature (℃)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350±10 (solder irno temp)	4~5	
2	Vapor phase reflow	215±5 (vapor temp)	60±5	
3	IR/convection reflow	255±5 (component temp)	30±5	1℃/s~4℃/s time above 183℃ 90s~120s

Note：The curve includes recommended value only, please adjust your equipment to make sure the solder process.Details please refers to the standard J-STD-020.

Reliability Test Criteria：

1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.

2 Solderbility: Dipped in 245℃+/-5℃ molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.

3 Resistance to soldering heat : Convection reflow condition setting: peak temperature at 260℃+0/-5℃ above 217℃ for 90-180 seconds, ramp-up rate 2-3℃/s. Ramp-down rate 6℃/s Max. No mechanical problem found. No electrical failure found per our specification.

4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.

5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.

6 Dry heat: 100+/-2℃ 96 hours.

7 Cold: -20+/-2℃ 96 hours.

8 Damp Heat: 60+/-2℃, 93+/-3% RH 96 hours.

9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at -20+/-2℃,2-3minutes at 20+/-2℃,30 minutes at 85+/-2℃, 2-3 minutes at 20+/-2℃.